

Application No.: 09/719,893

Case No.: 55259US005

Amendments to the Claims

The following Listing of Claims will replace all prior versions of claims in the application.

1. (Previously Presented) A heat conductive sheet including a substrate having a thickness from 1 to 7 μm and a self-supporting adhesive heat conductive resin layer applied to one surface of said substrate, wherein the heat conductive resin layer contains a binder resin, and a heat conductive filler dispersed in said binder resin.
2. (Original) A heat conductive sheet according to claim 1, wherein said substrate comprises a plastic film, a metal foil or a single spread adhesive film.
3. (Previously Presented) A heat conductive sheet according to claim 1, wherein said substrate comprises a polyolefin film or a polyester film.
4. (Original) A heat conductive sheet according to claim 1, wherein said heat conductive resin layer is formed by applying a film-forming resin composition to the surface of said substrate under the state where said substrate is held on a support.
5. (Previously Presented) A heat conductive sheet according to claim 1, wherein said binder resin comprises at least one resin selected from a silicone gel resin, a urethane resin, a synthetic rubber resin, and an acrylic thermoplastic resin.
6. (Original) A heat conductive sheet according to claim 1, wherein said binder resin comprises at least one of a silicone gel resin and a urethane resin.
7. (Original) A heat conductive sheet according to claim 1, wherein said heat conductive filler comprises an inorganic filler.

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8. (Previously Presented) A heat conductive sheet according to claim 1, wherein said heat conductive filler comprises two or more inorganic filler particles having mutually different particle diameters.

9. (Original) A heat conductive sheet according to claim 1, wherein said heat conductive filler comprises silicon carbide particles and boron nitride particles.

10. (Cancelled)

11. (Previously Presented) A heat conductive sheet according to claim 1, wherein said heat conductive resin layer is applied to only one surface of said substrate.

12. - 17. (Canceled)

18. (Currently Amended) A heat conductive sheet according to claim 1, wherein said substrate comprises a plastic film having a thickness from 1 to 7 μm , ~~a metal foil or a single spread adhesive film.~~

19. (Previously Presented) A heat conductive sheet according to claim 1, wherein said substrate comprises a metal foil having a thickness from 1 to 7 μm .

20. (Previously Presented) A heat conductive sheet according to claim 1, wherein said substrate comprises a single spread adhesive film having a thickness from 1 to 7 μm .

21. (Canceled)